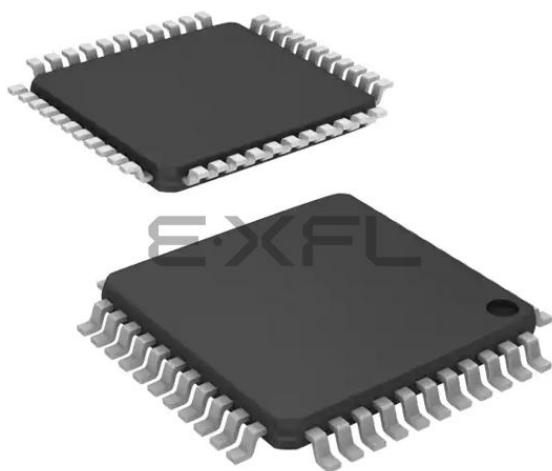




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Details

Product Status	Active
Core Processor	PIC
Core Size	8-Bit
Speed	20MHz
Connectivity	I ² C, SPI, UART/USART
Peripherals	Brown-out Detect/Reset, POR, PWM, WDT
Number of I/O	33
Program Memory Size	7KB (4K x 14)
Program Memory Type	OTP
EEPROM Size	-
RAM Size	256 x 8
Voltage - Supply (Vcc/Vdd)	4V ~ 5.5V
Data Converters	A/D 10x12b
Oscillator Type	External
Operating Temperature	0°C ~ 70°C (TA)
Mounting Type	Surface Mount
Package / Case	44-TQFP
Supplier Device Package	44-TQFP (10x10)
Purchase URL	https://www.e-xfl.com/product-detail/microchip-technology/pic16c774-pt

2.2.2.8 PCON REGISTER

The Power Control (PCON) register contains a flag bit to allow differentiation between a Power-on Reset (POR) to an external MCLR Reset or WDT Reset. Those devices with brown-out detection circuitry contain an additional bit to differentiate a Brown-out Reset condition from a Power-on Reset condition.

Note: $\overline{\text{BOR}}$ is unknown on Power-on Reset. It must then be set by the user and checked on subsequent resets to see if $\overline{\text{BOR}}$ is clear, indicating a brown-out has occurred. The $\overline{\text{BOR}}$ status bit is a don't care and is not necessarily predictable if the brown-out circuit is disabled (by clearing the BODEN bit in the Configuration word).

FIGURE 2-10: PCON REGISTER (ADDRESS 8Eh)

U-0	U-0	U-0	U-0	U-0	U-0	R/W-0	R/W-1
—	—	—	—	—	—	POR	$\overline{\text{BOR}}$
bit7							bit0

bit 7-2: **Unimplemented:** Read as '0'

bit 1: **POR:** Power-on Reset Status bit
1 = No Power-on Reset occurred
0 = A Power-on Reset occurred (must be set in software after a Power-on Reset occurs)

bit 0: **$\overline{\text{BOR}}$:** Brown-out Reset Status bit
1 = No Brown-out Reset occurred
0 = A Brown-out Reset occurred (must be set in software after a Brown-out Reset occurs)

R = Readable bit
W = Writable bit
U = Unimplemented bit, read as '0'
- n = Value at POR reset

TABLE 3-3 PORTB FUNCTIONS

Name	Bit#	Buffer	Function
RB0/INT	bit0	TTL/ST ⁽¹⁾	Input/output pin or external interrupt input. Internal software programmable weak pull-up.
RB1/SS	bit1	TTL/ST ⁽³⁾	Input/output pin or SSP slave select. Internal software programmable weak pull-up.
RB2/AN8	bit2	TTL	Input/output pin or analog input8. Internal software programmable weak pull-up.
RB3/AN9/LVDIN	bit3	TTL	Input/output pin or analog input9 or Low-voltage detect input. Internal software programmable weak pull-up.
RB4	bit4	TTL	Input/output pin (with interrupt on change). Internal software programmable weak pull-up.
RB5	bit5	TTL	Input/output pin (with interrupt on change). Internal software programmable weak pull-up.
RB6	bit6	TTL/ST ⁽²⁾	Input/output pin (with interrupt on change). Internal software programmable weak pull-up. Serial programming clock.
RB7	bit7	TTL/ST ⁽²⁾	Input/output pin (with interrupt on change). Internal software programmable weak pull-up. Serial programming data.

Legend: TTL = TTL input, ST = Schmitt Trigger input

Note 1: This buffer is a Schmitt Trigger input when configured as the external interrupt.

2: This buffer is a Schmitt Trigger input when used in serial programming mode.

3: This buffer is a Schmitt Trigger input when used as the SSP slave select.

TABLE 3-4 SUMMARY OF REGISTERS ASSOCIATED WITH PORTB

Address	Name	Bit 7	Bit 6	Bit 5	Bit 4	Bit 3	Bit 2	Bit 1	Bit 0	Value on: POR, BOR	Value on all other resets
06h, 106h	PORTB	RB7	RB6	RB5	RB4	RB3	RB2	RB1	RB0	xxxx 11xx	uuuu 11uu
86h, 186h	TRISB	PORTB Data Direction Register								1111 1111	1111 1111
81h, 181h	OPTION_REG	RBPU	INTEDG	T0CS	T0SE	PSA	PS2	PS1	PS0	1111 1111	1111 1111
9Fh	ADCON1	ADFM	VCFG2	VCFG1	VCFG0	PCFG3	PCFG2	PCFG1	PCFG0	0000 0000	0000 0000

Legend: x = unknown, u = unchanged. Shaded cells are not used by PORTB.

3.4 PORTD and TRISD Registers

This section is applicable to the 40/44-pin devices only.
PORTD is an 8-bit port with Schmitt Trigger input buffers. Each pin is individually configurable as an input or output.

PORTD can be configured as an 8-bit wide microprocessor port (parallel slave port) by setting control bit PSPMODE (TRISE<4>). In this mode, the input buffers are TTL.

FIGURE 3-10: PORTD BLOCK DIAGRAM (IN I/O PORT MODE)

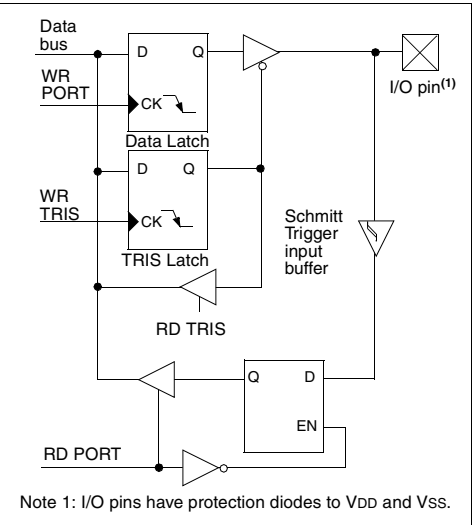


TABLE 3-7 PORTD FUNCTIONS

Name	Bit#	Buffer Type	Function
RD0/PSP0	bit0	ST/TTL ⁽¹⁾	Input/output port pin or parallel slave port bit0
RD1/PSP1	bit1	ST/TTL ⁽¹⁾	Input/output port pin or parallel slave port bit1
RD2/PSP2	bit2	ST/TTL ⁽¹⁾	Input/output port pin or parallel slave port bit2
RD3/PSP3	bit3	ST/TTL ⁽¹⁾	Input/output port pin or parallel slave port bit3
RD4/PSP4	bit4	ST/TTL ⁽¹⁾	Input/output port pin or parallel slave port bit4
RD5/PSP5	bit5	ST/TTL ⁽¹⁾	Input/output port pin or parallel slave port bit5
RD6/PSP6	bit6	ST/TTL ⁽¹⁾	Input/output port pin or parallel slave port bit6
RD7/PSP7	bit7	ST/TTL ⁽¹⁾	Input/output port pin or parallel slave port bit7

Legend: ST = Schmitt Trigger input TTL = TTL input

Note 1: Input buffers are Schmitt Triggers when in I/O mode and TTL buffer when in Parallel Slave Port Mode.

TABLE 3-8 SUMMARY OF REGISTERS ASSOCIATED WITH PORTD

Address	Name	Bit 7	Bit 6	Bit 5	Bit 4	Bit 3	Bit 2	Bit 1	Bit 0	Value on: POR, BOR	Value on all other resets
08h	PORTD	RD7	RD6	RD5	RD4	RD3	RD2	RD1	RD0	xxxx xxxx	uuuu uuuu
88h	TRISD	PORTD Data Direction Register								1111 1111	1111 1111
89h	TRISE	IBF	OBF	IBOV	PSPMODE	—	PORTE Data Direction Bits			0000 -111	0000 -111

Legend: x = unknown, u = unchanged, - = unimplemented read as '0'. Shaded cells are not used by PORTD.

5.2 Timer1 Oscillator

A crystal oscillator circuit is built in between pins T1OSI (input) and T1OSO (amplifier output). It is enabled by setting control bit T1OSCEN (T1CON<3>). The oscillator is a low power oscillator rated up to 200 kHz. It will continue to run during SLEEP. It is primarily intended for a 32 kHz crystal. Table 5-1 shows the capacitor selection for the Timer1 oscillator.

The Timer1 oscillator is identical to the LP oscillator. The user must provide a software time delay to ensure proper oscillator start-up.

TABLE 5-1 CAPACITOR SELECTION FOR THE TIMER1 OSCILLATOR

Osc Type	Freq	C1	C2
LP	32 kHz	33 pF	33 pF
	100 kHz	15 pF	15 pF
	200 kHz	15 pF	15 pF
These values are for design guidance only.			
Crystals Tested:			
32.768 kHz	Epson C-001R32.768K-A	± 20 PPM	
100 kHz	Epson C-2 100.00 KC-P	± 20 PPM	
200 kHz	STD XTL 200.000 kHz	± 20 PPM	
Note 1: Higher capacitance increases the stability of oscillator but also increases the start-up time.			
2: Since each resonator/crystal has its own characteristics, the user should consult the resonator/crystal manufacturer for appropriate values of external components.			

5.3 Timer1 Interrupt

The TMR1 Register pair (TMR1H:TMR1L) increments from 0000h to FFFFh and rolls over to 0000h. The TMR1 Interrupt, if enabled, is generated on overflow which is latched in interrupt flag bit TMR1IF (PIR1<0>). This interrupt can be enabled/disabled by setting/clearing TMR1 interrupt enable bit TMR1IE (PIE1<0>).

5.4 Resetting Timer1 using a CCP Trigger Output

If the CCP module is configured in compare mode to generate a "special event trigger" (CCP1M3:CCP1M0 = 1011), this signal will reset Timer1 and start an A/D conversion (if the A/D module is enabled).

Note: The special event triggers from the CCP1 module will not set interrupt flag bit TMR1IF (PIR1<0>).

Timer1 must be configured for either timer or synchronized counter mode to take advantage of this feature. If Timer1 is running in asynchronous counter mode, this reset operation may not work.

In the event that a write to Timer1 coincides with a special event trigger from CCP1, the write will take precedence.

In this mode of operation, the CCP1H:CCP1L registers pair effectively becomes the period register for Timer1.

TABLE 5-2 REGISTERS ASSOCIATED WITH TIMER1 AS A TIMER/COUNTER

Address	Name	Bit 7	Bit 6	Bit 5	Bit 4	Bit 3	Bit 2	Bit 1	Bit 0	Value on: POR, BOR	Value on all other resets
0Bh,8Bh,10Bh,18Bh	INTCON	GIE	PEIE	T0IE	INTE	RBIE	T0IF	INTF	RBIF	0000 000x	0000 000u
0Ch	PIR1	PSPIF ⁽¹⁾	ADIF	RCIF	TXIF	SSPIF	CCP1IF	TMR2IF	TMR1IF	0000 0000	0000 0000
8Ch	PIE1	PSPIE ⁽¹⁾	ADIE	RCIE	TXIE	SSPIE	CCP1IE	TMR2IE	TMR1IE	0000 0000	0000 0000
0Eh	TMR1L	Holding register for the Least Significant Byte of the 16-bit TMR1 register								xxxx xxxx	uuuu uuuu
0Fh	TMR1H	Holding register for the Most Significant Byte of the 16-bit TMR1 register								xxxx xxxx	uuuu uuuu
10h	T1CON	—	—	T1CKPS1	T1CKPS0	T1OSCEN	T1SYNC	TMR1CS	TMR1ON	--00 0000	--uu uuuu

Legend: x = unknown, u = unchanged, - = unimplemented read as '0'. Shaded cells are not used by the Timer1 module.

Note 1: These bits are reserved on the 28-pin devices, always maintain these bits clear.

6.0 TIMER2 MODULE

The Timer2 module timer has the following features:

- 8-bit timer (TMR2 register)
- 8-bit period register (PR2)
- Readable and writable (Both registers)
- Software programmable prescaler (1:1, 1:4, 1:16)
- Software programmable postscaler (1:1 to 1:16)
- Interrupt on TMR2 match of PR2
- SSP module optional use of TMR2 output to generate clock shift

Timer2 has a control register, shown in Figure 6-1. Timer2 can be shut off by clearing control bit TMR2ON (T2CON<2>) to minimize power consumption.

Figure 6-2 is a simplified block diagram of the Timer2 module.

Additional information on timer modules is available in the PICmicro™ Mid-Range Reference Manual, (DS33023).

6.1 Timer2 Operation

Timer2 can be used as the PWM time-base for PWM mode of the CCP module.

The TMR2 register is readable and writable, and is cleared on any device reset.

The input clock ($F_{osc}/4$) has a prescale option of 1:1, 1:4 or 1:16, selected by control bits T2CKPS1:T2CKPS0 (T2CON<1:0>).

The match output of TMR2 goes through a 4-bit postscaler (which gives a 1:1 to 1:16 scaling inclusive) to generate a TMR2 interrupt (latched in flag bit TMR2IF, (PIR1<1>)).

The prescaler and postscaler counters are cleared when any of the following occurs:

- a write to the TMR2 register
- a write to the T2CON register
- any device reset (Power-on Reset, $\overline{MCLR}$ reset, Watchdog Timer reset, or Brown-out Reset)

TMR2 is not cleared when T2CON is written.

FIGURE 6-1: T2CON: TIMER2 CONTROL REGISTER (ADDRESS 12h)

U-0	R/W-0	R/W-0	R/W-0	R/W-0	R/W-0	R/W-0	R/W-0
—	TOUTPS3	TOUTPS2	TOUTPS1	TOUTPS0	TMR2ON	T2CKPS1	T2CKPS0
bit7				bit0			

R = Readable bit
W = Writable bit
U = Unimplemented bit, read as '0'
- n = Value at POR reset

bit 7: **Unimplemented:** Read as '0'

bit 6-3: **TOUTPS3:TOUTPS0:** Timer2 Output Postscale Select bits
0000 = 1:1 Postscale
0001 = 1:2 Postscale
•
•
•
1111 = 1:16 Postscale

bit 2: **TMR2ON:** Timer2 On bit
1 = Timer2 is on
0 = Timer2 is off

bit 1-0: **T2CKPS1:T2CKPS0:** Timer2 Clock Prescale Select bits
00 = Prescaler is 1
01 = Prescaler is 4
1x = Prescaler is 16

determine when the transmission/reception has completed. The SSPBUF must be read and/or written. If the interrupt method is not going to be used, then software polling can be done to ensure that a write collision does not occur. Example 8-1 shows the loading of the SSPBUF (SSPSR) for data transmission.

EXAMPLE 8-1: LOADING THE SSPBUF (SSPSR) REGISTER

```
BSF    STATUS, RP0    ;Specify Bank 1
LOOP  BTFS    SSPSTAT, BF    ;Has data been
                                ;received
                                ;(transmit
                                ;complete)?
GOTO   LOOP           ;No
BCF    STATUS, RP0    ;Specify Bank 0
MOVF   SSPBUF, W      ;W reg = contents
                                ;of SSPBUF
MOVWF  RXDATA         ;Save in user RAM
MOVF   TXDATA, W      ;W reg = contents
                                ; of TXDATA
MOVWF  SSPBUF         ;New data to xmit
```

The SSPSR is not directly readable or writable, and can only be accessed by addressing the SSPBUF register. Additionally, the MSSP status register (SSPSTAT) indicates the various status conditions.

8.1.2 ENABLING SPI I/O

To enable the serial port, MSSP Enable bit, SSPEN (SSPCON<5>) must be set. To reset or reconfigure SPI mode, clear bit SSPEN, re-initialize the SSPCON registers, and then set bit SSPEN. This configures the

SDI, SDO, SCK, and $\overline{SS}$ pins as serial port pins. For the pins to behave as the serial port function, some must have their data direction bits (in the TRIS register) appropriately programmed. That is:

- SDI is automatically controlled by the SPI module
- SDO must have TRISC<5> cleared
- SCK (Master mode) must have TRISC<3> cleared
- SCK (Slave mode) must have TRISC<3> set
- $\overline{SS}$ must have TRISA<5> set

Any serial port function that is not desired may be overridden by programming the corresponding data direction (TRIS) register to the opposite value.

8.1.3 TYPICAL CONNECTION

Figure 8-5 shows a typical connection between two microcontrollers. The master controller (Processor 1) initiates the data transfer by sending the SCK signal. Data is shifted out of both shift registers on their programmed clock edge, and latched on the opposite edge of the clock. Both processors should be programmed to same Clock Polarity (CKP), then both controllers would send and receive data at the same time. Whether the data is meaningful (or dummy data) depends on the application software. This leads to three scenarios for data transmission:

- Master sends data — Slave sends dummy data
- Master sends data — Slave sends data
- Master sends dummy data — Slave sends data

FIGURE 8-5: SPI MASTER/SLAVE CONNECTION

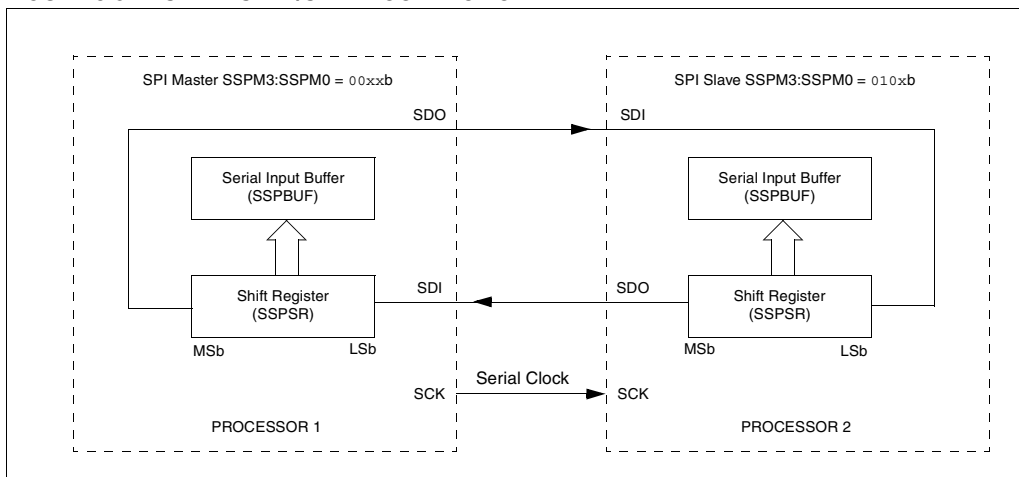


FIGURE 8-24: REPEATED START CONDITION FLOWCHART (PAGE 2)

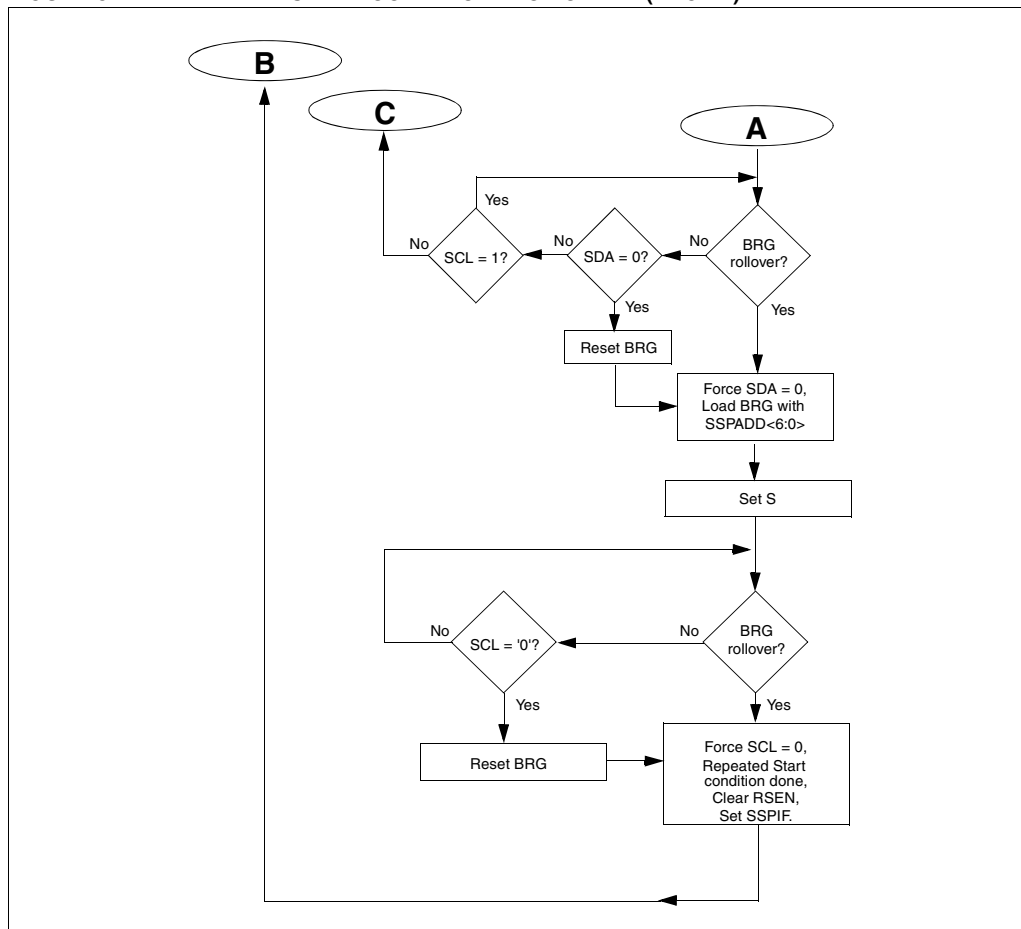


FIGURE 8-30: ACKNOWLEDGE FLOWCHART

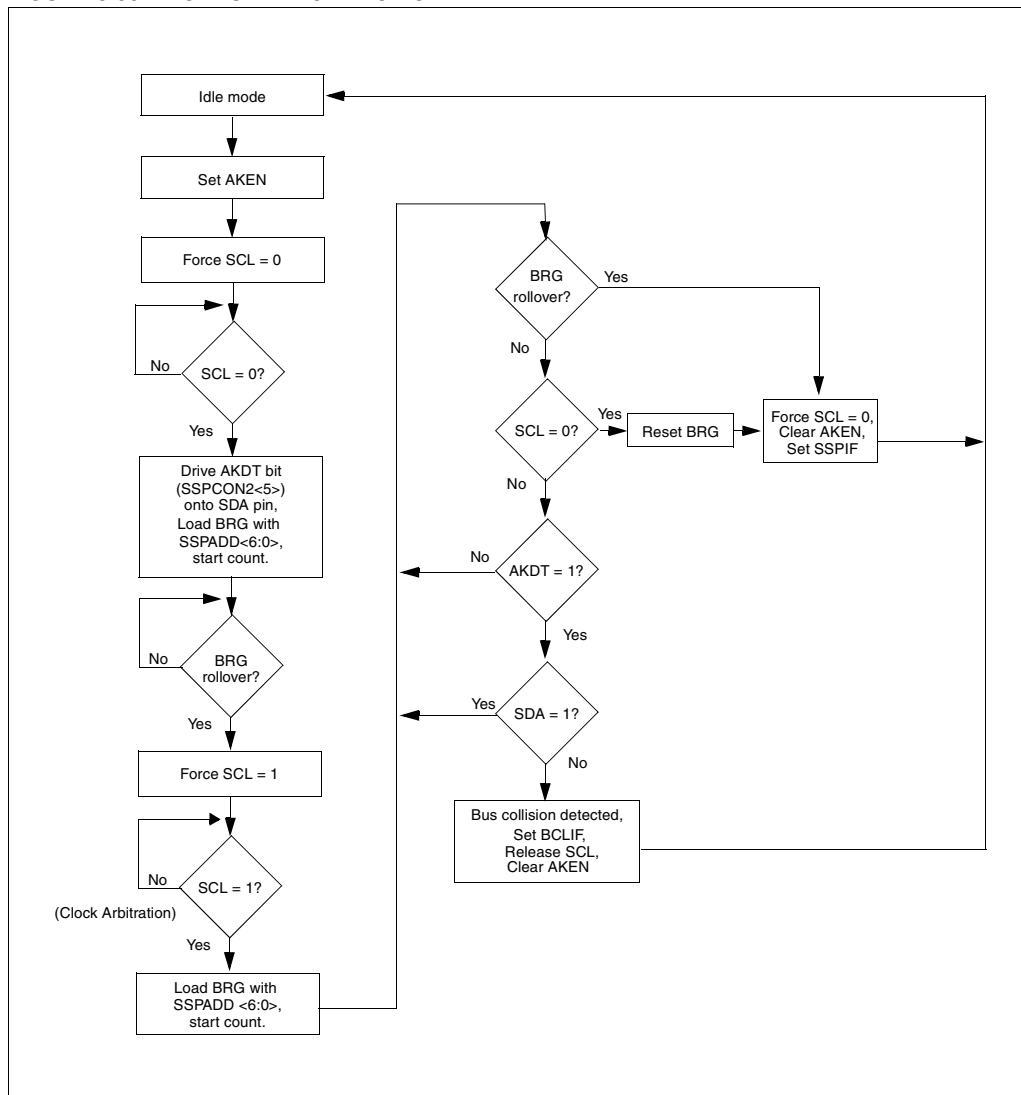


FIGURE 8-36: BUS COLLISION DURING START CONDITION (SCL = 0)

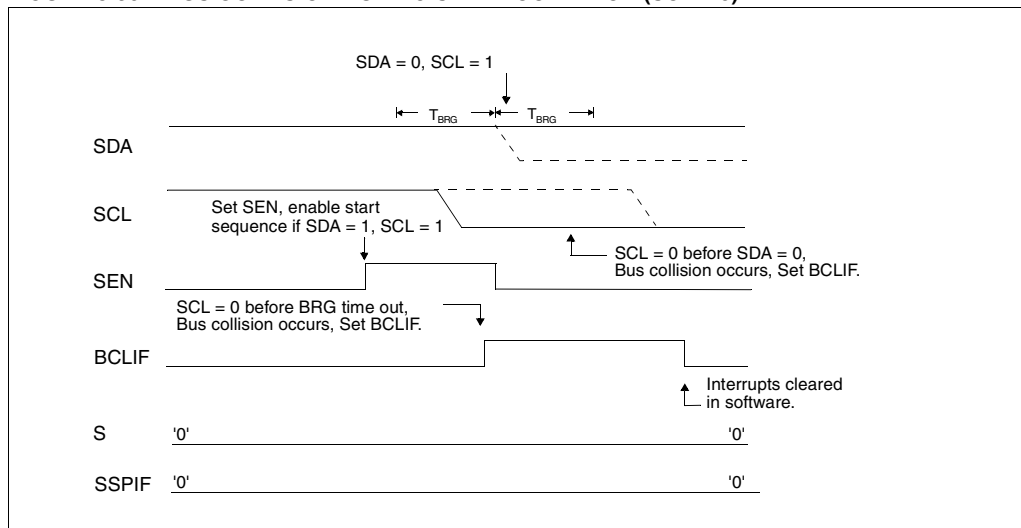
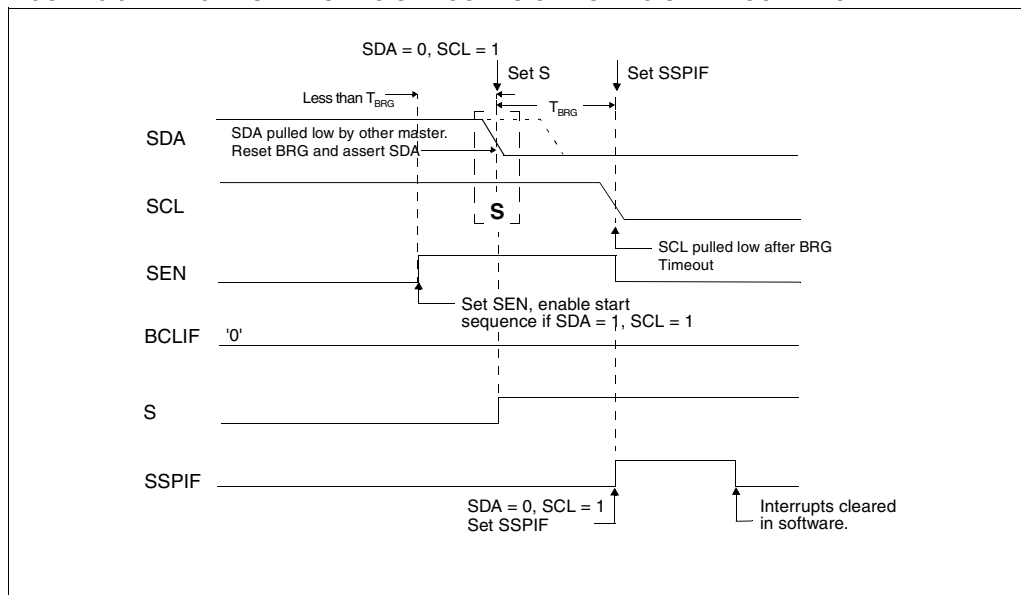


FIGURE 8-37: BRG RESET DUE TO SDA COLLISION DURING START CONDITION



9.0 ADDRESSABLE UNIVERSAL SYNCHRONOUS ASYNCHRONOUS RECEIVER TRANSMITTER (USART)

The Universal Synchronous Asynchronous Receiver Transmitter (USART) module is one of the two serial I/O modules. (USART is also known as a Serial Communications Interface or SCI). The USART can be configured as a full duplex asynchronous system that can communicate with peripheral devices such as CRT terminals and personal computers, or it can be configured as a half duplex synchronous system that can communicate with peripheral devices such as A/D or D/A integrated circuits, Serial EEPROMs etc.

The USART can be configured in the following modes:

- Asynchronous (full duplex)
- Synchronous - Master (half duplex)
- Synchronous - Slave (half duplex)

Bit SPEN (RCSTA<7>), and bits TRISC<7:6>, have to be set in order to configure pins RC6/TX/CK and RC7/RX/DT as the Universal Synchronous Asynchronous Receiver Transmitter.

The USART module also has a multi-processor communication capability using 9-bit address detection.

FIGURE 9-1: TXSTA: TRANSMIT STATUS AND CONTROL REGISTER (ADDRESS 98h)

R/W-0	R/W-0	R/W-0	R/W-0	U-0	R/W-0	R-1	R/W-0
CSRC	TX9	TXEN	SYNC	—	BRGH	TRMT	TX9D
bit7							bit0
bit 7: CSRC: Clock Source Select bit <u>Asynchronous mode</u> Don't care <u>Synchronous mode</u> 1 = Master mode (Clock generated internally from BRG) 0 = Slave mode (Clock from external source) bit 6: TX9: 9-bit Transmit Enable bit 1 = Selects 9-bit transmission 0 = Selects 8-bit transmission bit 5: TXEN: Transmit Enable bit 1 = Transmit enabled 0 = Transmit disabled Note: SREN/CREN overrides TXEN in SYNC mode. bit 4: SYNC: USART Mode Select bit 1 = Synchronous mode 0 = Asynchronous mode bit 3: Unimplemented: Read as '0' bit 2: BRGH: High Baud Rate Select bit <u>Asynchronous mode</u> 1 = High speed 0 = Low speed <u>Synchronous mode</u> Unused in this mode bit 1: TRMT: Transmit Shift Register Status bit 1 = TSR empty 0 = TSR full bit 0: TX9D: 9th bit of transmit data. Can be parity bit. R = Readable bit W = Writable bit U = Unimplemented bit, read as '0' - n =Value at POR reset							

FIGURE 9-8: ASYNCHRONOUS RECEPTION WITH ADDRESS BYTE FIRST

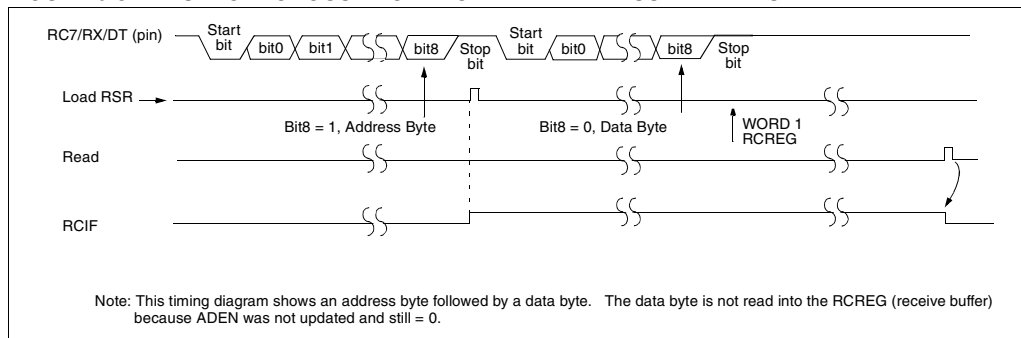


TABLE 9-7 REGISTERS ASSOCIATED WITH ASYNCHRONOUS RECEPTION

Address	Name	Bit 7	Bit 6	Bit 5	Bit 4	Bit 3	Bit 2	Bit 1	Bit 0	Value on: POR, BOR	Value on all other Resets
0Ch	PIR1	PSPIF ⁽¹⁾	ADIF	RCIF	TXIF	SSPIF	CCP1IF	TMR2IF	TMR1IF	0000 0000	0000 0000
18h	RCSTA	SPEN	RX9	SREN	CREN	ADDEN	FERR	OERR	RX9D	0000 000x	0000 000x
1Ah	RCREG	USART Receive Register								0000 0000	0000 0000
8Ch	PIE1	PSPIE ⁽¹⁾	ADIE	RCIE	TXIE	SSPIE	CCP1IE	TMR2IE	TMR1IE	0000 0000	0000 0000
98h	TXSTA	CSRC	TX9	TXEN	SYNC	—	BRGH	TRMT	TX9D	0000 -010	0000 -010
99h	SPBRG	Baud Rate Generator Register								0000 0000	0000 0000

Legend: x = unknown, - = unimplemented locations read as '0'. Shaded cells are not used for Asynchronous Reception.

Note 1: Bits PSPIE and PSPIF are reserved on the 28-pin devices, always maintain these bits clear.

10.0 VOLTAGE REFERENCE MODULE AND LOW-VOLTAGE DETECT

The Voltage Reference module provides reference voltages for the Brown-out Reset circuitry, the Low-voltage Detect circuitry and the A/D converter.

The source for the reference voltages comes from the bandgap reference circuit. The bandgap circuit is energized anytime the reference voltage is required by the other sub-modules, and is powered down when not in use. The control registers for this module are LVDCON and REFCON, as shown in Figure 10-1 and Figure 10-2.

FIGURE 10-1: LVDCON: LOW-VOLTAGE DETECT CONTROL REGISTER

U-0	U-0	R-0	R/W-0	R/W-0	R/W-1	R/W-0	R/W-1
—	—	BGST	LVDEN	LV3	LV2	LV1	LV0
bit7		bit0					

R = Readable bit
W = Writable bit
U = Unimplemented bit, read as '0'
- n = Value at POR reset

bit 7-6: **Unimplemented:** Read as '0'

bit 5: **BGST:** Bandgap Stable Status Flag bit
1 = Indicates that the bandgap voltage is stable, and LVD interrupt is reliable
0 = Indicates that the bandgap voltage is not stable, and LVD interrupt should not be enabled

bit 4: **LVDEN:** Low-voltage Detect Power Enable bit
1 = Enables LVD, powers up bandgap circuit and reference generator
0 = Disables LVD, powers down bandgap circuit if unused by BOR or VRH/VRL

bit 3-0: **LV3:LV0:** Low Voltage Detection Limit bits ⁽¹⁾
1111 = External analog input is used
1110 = 4.5V
1101 = 4.2V
1100 = 4.0V
1011 = 3.8V
1010 = 3.6V
1001 = 3.5V
1000 = 3.3V
0111 = 3.0V
0110 = 2.8V
0101 = 2.7V
0100 = 2.5V

Note 1: These are the minimum trip points for the LVD, see Table 15-3 for the trip point tolerances. Selection of an unused setting may result in an inadvertant interrupt.

The value that is in the ADRESH and ADRESL registers are not modified for a Power-on Reset. The ADRESH and ADRESL registers will contain unknown data after a Power-on Reset.

After the A/D module has been configured as desired, the selected channel must be acquired before the conversion is started. The analog input channels must have their corresponding TRIS bits selected as an input. To determine acquisition time, see Section 11.6. After this acquisition time has elapsed the A/D conversion can be started. The following steps should be followed for doing an A/D conversion:

11.2 Configuring the A/D Module

11.3 Configuring Analog Port Pins

The ADCON1 and TRIS registers control the operation of the A/D port pins. The port pins that are desired as analog inputs must have their corresponding TRIS bit set (input). If the TRIS bit is cleared (output), the digital output level (VOH or VOL) will be converted.

The A/D operation is independent of the state of the CHS3:CHS0 bits and the TRIS bits.

Note 1: When reading the PORTA or PORTE register, all pins configured as analog input channels will read as cleared (a low level). When reading the PORTB register, all pins configured as analog input channels will read as set (a high level). Pins configured as digital inputs, will convert an analog input. Analog levels on a digitally configured input will not affect the conversion accuracy.

Note 2: Analog levels on any pin that is defined as a digital input (including the ANx pins), may cause the input buffer to consume current that is out of the devices specification.

11.3.1 CONFIGURING THE REFERENCE VOLTAGES

The VCFG bits in the ADCON1 register configure the A/D module reference inputs. The reference high input can come from an internal reference (VRH) or (VRL), an external reference (VREF+), or AVDD. The low reference input can come from an internal reference (VRL), an external reference (VREF-), or AVSS. If an external reference is chosen for the reference high or reference low inputs, the port pin that multiplexes the incoming external references is configured as an analog input, regardless of the values contained in the A/D port configuration bits (PCFG3:PCFG0).

After the A/D module has been configured as desired, and the analog input channels have their corresponding TRIS bits selected for port inputs, the selected channel must be acquired before conversion is started. The A/D conversion cycle can be initiated by setting the GO/DONE bit. The A/D conversion begins, and lasts for 13TAD. The following steps should be followed for performing an A/D conversion:

1. Configure the A/D module
 - Configure analog pins / voltage reference / and digital I/O (ADCON1)
 - Select A/D input channel (ADCON0)
 - Select A/D conversion clock (ADCON0)
 - Turn on A/D module (ADCON0)
2. Configure A/D interrupt (if required)
 - Clear ADIF bit
 - Set ADIE bit
 - Set PEIE bit
 - Set GIE bit
3. Wait the required acquisition time (3TAD)
4. Start conversion
 - Set GO/DONE bit (ADCON0)
5. Wait 13TAD until A/D conversion is complete, by either:
 - Polling for the GO/DONE bit to be cleared
 OR
 - Waiting for the A/D interrupt
6. Read A/D Result registers (ADRESH and ADRESL), clear ADIF if required.
7. For next conversion, go to step 1, step 2 or step 3 as required.

Clearing the GO/DONE bit during a conversion will abort the current conversion. The ADRESH and ADRESL registers **WILL** be updated with the partially completed A/D conversion value. That is, the ADRESH and ADRESL registers **WILL** contain the value of the current incomplete conversion.

Note: Do not set the ADON bit and the GO/DONE bit in the same instruction. Doing so will cause the GO/DONE bit to be automatically cleared.

FIGURE 11-7: CALCULATING THE MINIMUM REQUIRED SAMPLE TIME

$$\begin{aligned} T_{ACQ} &= \text{Amplifier Settling Time} \\ &+ \text{Holding Capacitor Charging Time} \\ &+ \text{Temperature Coefficient } \uparrow \\ T_{ACQ} &= 5 \mu\text{s} \\ &+ T_C \\ &+ [(Temp - 25^\circ\text{C})(0.05 \mu\text{s}/^\circ\text{C})] \uparrow \\ T_C &= + \text{Holding Capacitor Charging Time} \\ T_C &= (CHOLD) (R_{IC} + R_{SS} + R_S) \ln (1/16384) \\ T_C &= -25 \text{ pF} (1 \text{ k}\Omega + 10 \text{ k}\Omega + 2.5 \text{ k}\Omega) \ln (1/16384) \\ T_C &= -25 \text{ pF} (13.5 \text{ k}\Omega) \ln (1/16384) \\ T_C &= -0.338 (-9.704) \mu\text{s} \\ T_C &= 3.3 \mu\text{s} \end{aligned}$$

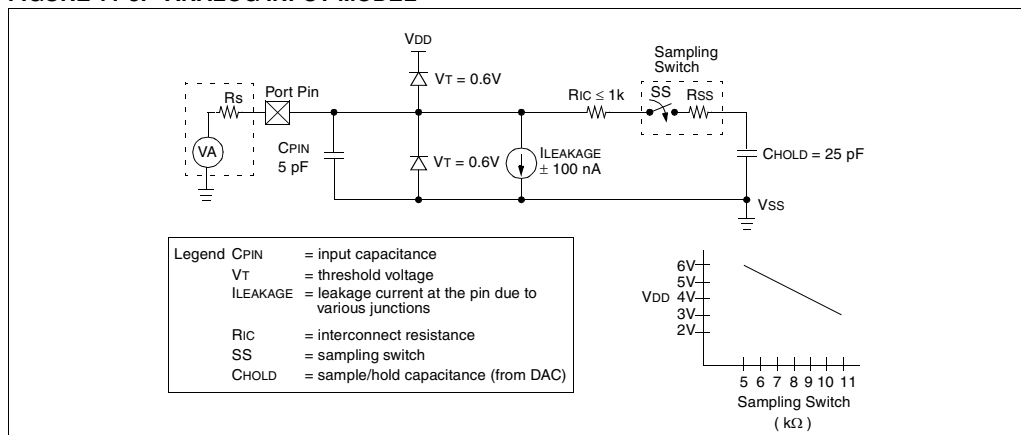
$$\begin{aligned} T_{ACQ} &= 5 \mu\text{s} \\ &+ 3.3 \mu\text{s} \\ &+ [(50^\circ\text{C} - 25^\circ\text{C})(0.05 \mu\text{s} / ^\circ\text{C})] \end{aligned}$$

$$T_{ACQ} = 8.3 \mu\text{s} + 1.25 \mu\text{s}$$

$$T_{ACQ} = 9.55 \mu\text{s}$$

† The temperature coefficient is only required for temperatures > 25°C.

FIGURE 11-8: ANALOG INPUT MODEL



12.10 Interrupts

The PIC16C77X family has up to 14 sources of interrupt. The interrupt control register (INTCON) records individual interrupt requests in flag bits. It also has individual and global interrupt enable bits.

Note: Individual interrupt flag bits are set regardless of the status of their corresponding mask bit or the GIE bit.

A global interrupt enable bit, GIE (INTCON<7>) enables (if set) all un-masked interrupts or disables (if cleared) all interrupts. When bit GIE is enabled, and an interrupt's flag bit and mask bit are set, the interrupt will vector immediately. Individual interrupts can be disabled through their corresponding enable bits in various registers. Individual interrupt bits are set regardless of the status of the GIE bit. The GIE bit is cleared on reset.

The "return from interrupt" instruction, RETFIE, exits the interrupt routine as well as sets the GIE bit, which re-enables interrupts.

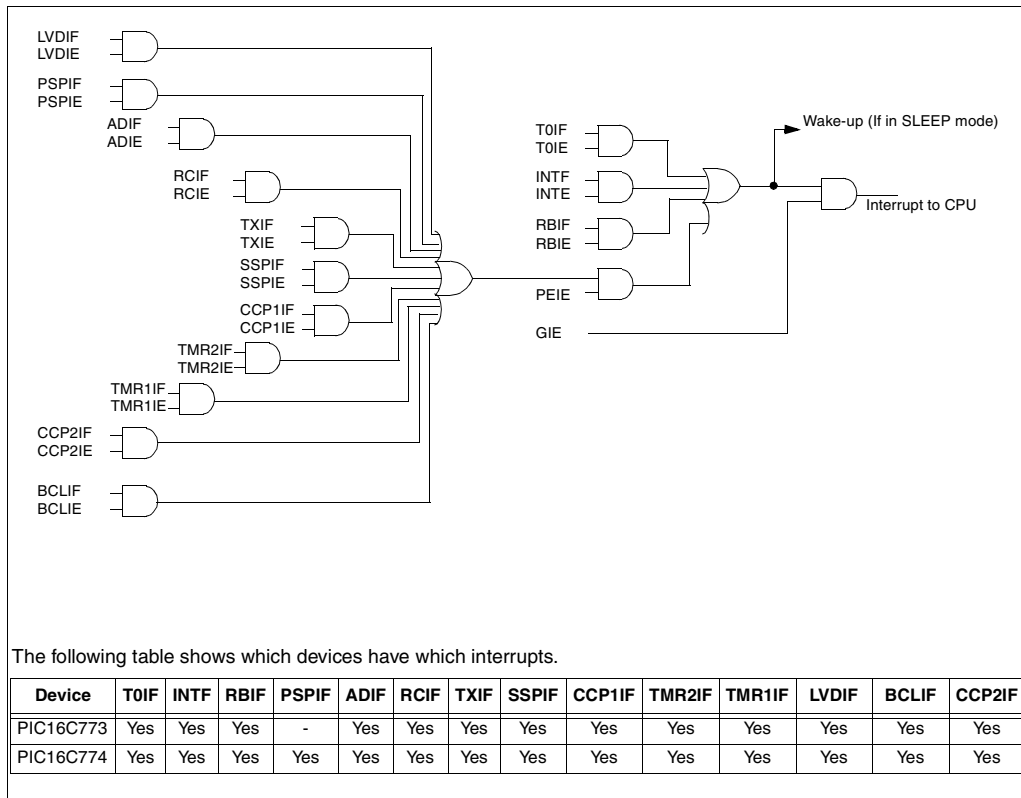
The RB0/INT pin interrupt, the RB port change interrupt and the TMR0 overflow interrupt flags are contained in the INTCON register.

The peripheral interrupt flags are contained in the special function registers PIR1 and PIR2. The corresponding interrupt enable bits are contained in special function registers PIE1 and PIE2, and the peripheral interrupt enable bit is contained in special function register INTCON.

When an interrupt is responded to, the GIE bit is cleared to disable any further interrupt, the return address is pushed onto the stack and the PC is loaded with 0004h. Once in the interrupt service routine the source(s) of the interrupt can be determined by polling the interrupt flag bits. The interrupt flag bit(s) must be cleared in software before re-enabling interrupts to avoid recursive interrupts.

For external interrupt events, such as the INT pin or PORTB change interrupt, the interrupt latency will be three or four instruction cycles. The exact latency depends when the interrupt event occurs. The latency is the same for one or two cycle instructions. Individual interrupt flag bits are set regardless of the status of their corresponding mask bit or the GIE bit

FIGURE 12-11: INTERRUPT LOGIC



12.13 Power-down Mode (SLEEP)

Power-down mode is entered by executing a `SLEEP` instruction.

If enabled, the Watchdog Timer will be cleared but keeps running, the $\overline{PD}$ bit (`STATUS<3>`) is cleared, the $\overline{TO}$ (`STATUS<4>`) bit is set, and the oscillator driver is turned off. The I/O ports maintain the status they had, before the `SLEEP` instruction was executed (driving high, low, or hi-impedance).

For lowest current consumption in this mode, place all I/O pins at either V_{DD} , or V_{SS} , ensure no external circuitry is drawing current from the I/O pin, power-down the A/D, disable external clocks. Pull all I/O pins, that are hi-impedance inputs, high or low externally to avoid switching currents caused by floating inputs. The $\overline{TOCKI}$ input should also be at V_{DD} or V_{SS} for lowest current consumption. The contribution from on-chip pull-ups on `PORTB` should be considered.

The $\overline{MCLR}$ pin must be at a logic high level (V_{IHMC}).

12.13.1 WAKE-UP FROM SLEEP

The device can wake up from `SLEEP` through one of the following events:

1. External reset input on $\overline{MCLR}$ pin.
2. Watchdog Timer Wake-up (if `WDT` was enabled).
3. Interrupt from `INT` pin, `RB` port change, or some Peripheral Interrupts.

External $\overline{MCLR}$ Reset will cause a device reset. All other events are considered a continuation of program execution and cause a "wake-up". The $\overline{TO}$ and $\overline{PD}$ bits in the `STATUS` register can be used to determine the cause of device reset. The $\overline{PD}$ bit, which is set on power-up, is cleared when `SLEEP` is invoked. The $\overline{TO}$ bit is cleared if a `WDT` time-out occurred (and caused wake-up).

The following peripheral interrupts can wake the device from `SLEEP`:

1. `PSP` read or write.
2. `TMR1` interrupt. `Timer1` must be operating as an asynchronous counter.
3. `CCP` capture mode interrupt.
4. Special event trigger (`Timer1` in asynchronous mode using an external clock).
5. `SSP` (Start/Stop) bit detect interrupt.
6. `SSP` transmit or receive in slave mode (`SPI/I2C`).
7. `USART` RX or TX (synchronous slave mode).
8. A/D conversion (when A/D clock source is `RC`).
9. Low-voltage detect.

Other peripherals cannot generate interrupts since during `SLEEP`, no on-chip clocks are present.

When the `SLEEP` instruction is being executed, the next instruction (`PC + 1`) is pre-fetched. For the device to wake-up through an interrupt event, the corresponding interrupt enable bit must be set (enabled). Wake-up is regardless of the state of the `GIE` bit. If the `GIE` bit is clear (disabled), the device continues execution at the instruction after the `SLEEP` instruction. If the `GIE` bit is set (enabled), the device executes the instruction after the `SLEEP` instruction and then branches to the interrupt address (0004h). In cases where the execution of the instruction following `SLEEP` is not desirable, the user should have a `NOP` after the `SLEEP` instruction.

12.13.2 WAKE-UP USING INTERRUPTS

When global interrupts are disabled (`GIE` cleared) and any interrupt source has both its interrupt enable bit and interrupt flag bit set, one of the following will occur:

- If the interrupt occurs **before** the execution of a `SLEEP` instruction, the `SLEEP` instruction will complete as a `NOP`. Therefore, the `WDT` and `WDT` postscaler will not be cleared, the $\overline{TO}$ bit will not be set and $\overline{PD}$ bits will not be cleared.
- If the interrupt occurs **during or after** the execution of a `SLEEP` instruction, the device will immediately wake up from sleep. The `SLEEP` instruction will be completely executed before the wake-up. Therefore, the `WDT` and `WDT` postscaler will be cleared, the $\overline{TO}$ bit will be set and the $\overline{PD}$ bit will be cleared.

Even if the flag bits were checked before executing a `SLEEP` instruction, it may be possible for flag bits to become set before the `SLEEP` instruction completes. To determine whether a `SLEEP` instruction executed, test the $\overline{PD}$ bit. If the $\overline{PD}$ bit is set, the `SLEEP` instruction was executed as a `NOP`.

To ensure that the `WDT` is cleared, a `CLRWDT` instruction should be executed before a `SLEEP` instruction.

Standard Operating Conditions (unless otherwise stated)							
Operating temperature -40°C ≤ TA ≤ +85°C for industrial and 0°C ≤ TA ≤ +70°C for commercial							
Operating voltage VDD range as described in DC spec Section 15.1 and Section 15.2.							
Param No.	Characteristic	Sym	Min	Typ†	Max	Units	Conditions
D090	Output High Voltage I/O ports (Note 3)	VOH	VDD - 0.7	—	—	V	IOH = -3.0 mA, VDD = 4.5V, -40°C to +85°C
D092	OSC2/CLKOUT (RC osc config)		VDD - 0.7	—	—	V	
D150*	Open-Drain High Voltage	VOD	—	—	8.5	V	RA4 pin
Capacitive Loading Specs on Output Pins							
D100	OSC2 pin	Cosc2	—	—	15	pF	In XT, HS and LP modes when external clock is used to drive OSC1.
D101	All I/O pins and OSC2 (in RC mode) SCL, SDA in I ² C mode	Cio	—	—	50	pF	
D102		Cb	—	—	400	pF	

* These parameters are characterized but not tested.

† Data in "Typ" column is at 5V, 25°C unless otherwise stated. These parameters are for design guidance only and are not tested.

Note 1: In RC oscillator configuration, the OSC1/CLKIN pin is a Schmitt Trigger input. It is not recommended that the PIC16C77X be driven with external clock in RC mode.

2: The leakage current on the MCLR pin is strongly dependent on the applied voltage level. The specified levels represent normal operating conditions. Higher leakage current may be measured at different input voltages.

3: Negative current is defined as current sourced by the pin.

TABLE 15-9 A/D CONVERTER CHARACTERISTICS:

Param No.	Sym	Characteristic	Min	Typ†	Max	Units	Conditions
A01	NR	Resolution	—	—	12 bits	bit	Min. resolution for A/D is 1 mV, VREF+ = AVDD = 4.096V, VREF- = AVSS = 0V, VREF- ≤ VAIN ≤ VREF+
A03	EIL	Integral error	—	—	+/- 2 LSb	—	VREF+ = AVDD = 4.096V, VREF- = AVSS = 0V, VREF- ≤ VAIN ≤ VREF+
A04	EDL	Differential error	—	—	+2 LSb -1 LSb	—	No missing codes to 12-bits VREF+ = AVDD = 4.096V, VREF- = AVSS = 0V, VREF- ≤ VAIN ≤ VREF+
A06	EOFF	Offset error	—	—	less than ±2 LSb	—	VREF+ = AVDD = 4.096V, VREF- = AVSS = 0V, VREF- ≤ VAIN ≤ VREF+
A07	EGN	Gain Error	—	—	+/- 2LSb	LSb	VREF+ = AVDD = 4.096V, VREF- = AVSS = 0V, VREF- ≤ VAIN ≤ VREF+
A10	—	Monotonicity	—	guaranteed ⁽³⁾	—	—	AVSS ≤ VAIN ≤ VREF+
A20	VREF	Reference voltage (VREF+ - VREF-)	4.096	—	VDD +0.3V	V	Absolute minimum electrical spec to ensure 12-bit accuracy.
A21	VREF+	Reference V High (AVDD or VREF+)	VREF-	—	AVDD	V	Min. resolution for A/D is 1 mV
A22	VREF-	Reference V Low (AVSS or VREF-)	AVSS	—	VREF+	V	Min. resolution for A/D is 1 mV
A25	VAIN	Analog input voltage	VREFL	—	VREFH	V	
A30	ZAIN	Recommended impedance of analog voltage source	—	—	2.5	kΩ	
A50	IREF	VREF input current (Note 2)	—	—	10	μA	During VAIN acquisition. Based on differential of VHOLD to VAIN. To charge CHOLD see Section 11.0. During A/D conversion cycle.

* These parameters are characterized but not tested.

† Data in "Typ" column is at 5V, 25°C unless otherwise stated. These parameters are for design guidance only and are not tested.

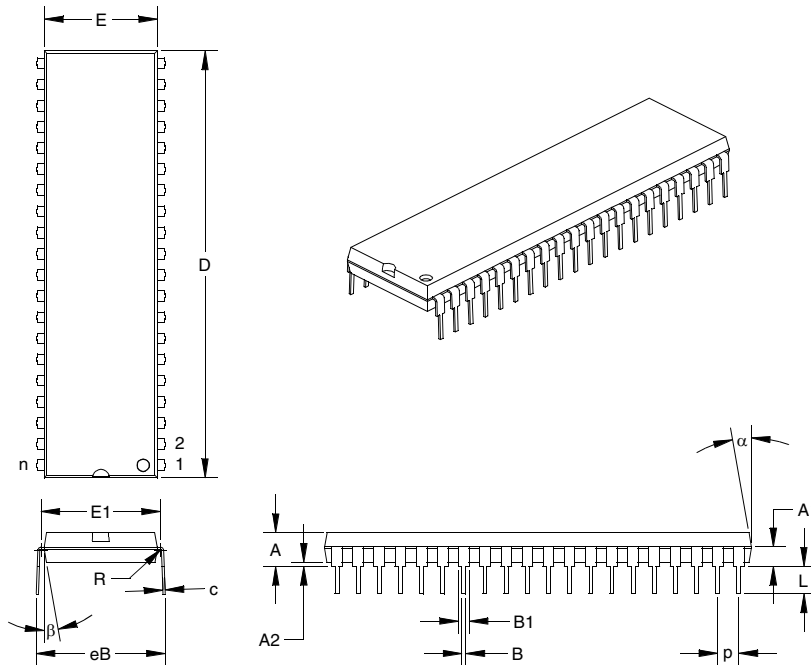
Note 1: When A/D is off, it will not consume any current other than minor leakage current. The power down current spec includes any such leakage from the A/D module.

2: VREF current is from External VREF+, or VREF-, or AVSS, or AVDD pin, whichever is selected as reference input.

3: The A/D conversion result never decreases with an increase in the input voltage and has no missing codes.

17.6 K04-016 40-Lead Plastic Dual In-line (P) – 600 mil

Note: For the most current package drawings, please see the Microchip Packaging Specification located at <http://www.microchip.com/packaging>



Units		INCHES*			MILLIMETERS		
Dimension Limits		MIN	NOM	MAX	MIN	NOM	MAX
PCB Row Spacing			0.600			15.24	
Number of Pins	n		40			40	
Pitch	p		0.100			2.54	
Lower Lead Width	B	0.016	0.018	0.020	0.41	0.46	0.51
Upper Lead Width	B1†	0.045	0.050	0.055	1.14	1.27	1.40
Shoulder Radius	R	0.000	0.005	0.010	0.00	0.13	0.25
Lead Thickness	c	0.009	0.010	0.011	0.23	0.25	0.28
Top to Seating Plane	A	0.110	0.160	0.160	2.79	4.06	4.06
Top of Lead to Seating Plane	A1	0.073	0.093	0.113	1.85	2.36	2.87
Base to Seating Plane	A2	0.020	0.020	0.040	0.51	0.51	1.02
Tip to Seating Plane	L	0.125	0.130	0.135	3.18	3.30	3.43
Package Length	D‡	2.013	2.018	2.023	51.13	51.26	51.38
Molded Package Width	E‡	0.530	0.535	0.540	13.46	13.59	13.72
Radius to Radius Width	E1	0.545	0.565	0.585	13.84	14.35	14.86
Overall Row Spacing	eB	0.630	0.610	0.670	16.00	15.49	17.02
Mold Draft Angle Top	α	5	10	15	5	10	15
Mold Draft Angle Bottom	β	5	10	15	5	10	15

* Controlling Parameter.

† Dimension "B1" does not include dam-bar protrusions. Dam-bar protrusions shall not exceed 0.003" (0.076 mm) per side or 0.006" (0.152 mm) more than dimension "B1."

‡ Dimensions "D" and "E" do not include mold flash or protrusions. Mold flash or protrusions shall not exceed 0.010" (0.254 mm) per side or 0.020" (0.508 mm) more than dimensions "D" or "E."

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